

KP-1608P1C

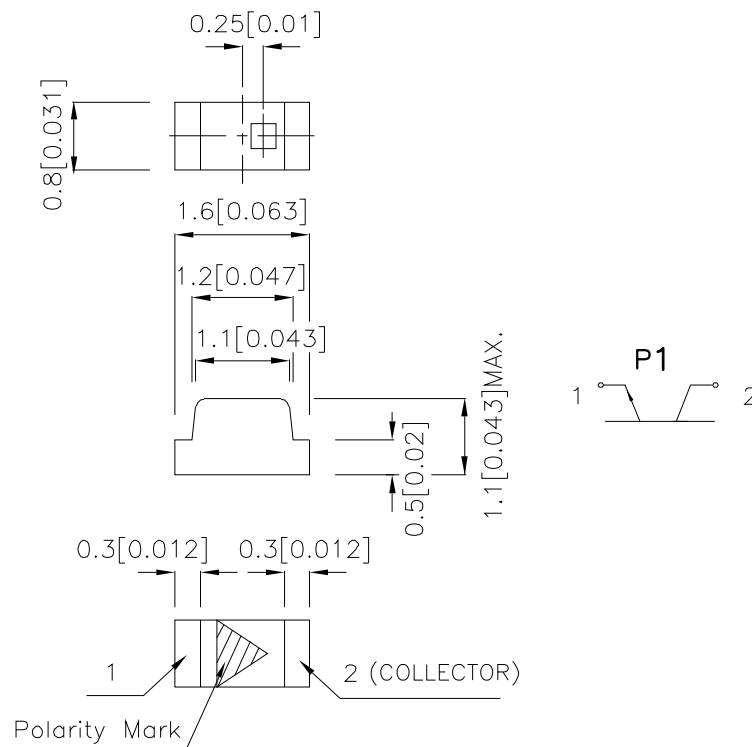
### Features

- 1.6mmX0.8mm SMT LED, 1.1mm THICKNESS.
- MECHANICALLY AND SPECTRALLY MATCHED TO THE KP-1608 SERIES INFRARED EMITTING LED LAMP.
- WATER CLEAR LENS.
- PACKAGE: 2000PCS / REEL .
- RoHS COMPLIANT.

### Description

Made with NPN silicon phototransistor chips.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is  $\pm 0.1$  (0.004") unless otherwise noted.
3. Specifications are subject to change without notice.

## Electrical / Optical Characteristics at $T_A=25^{\circ}\text{C}$

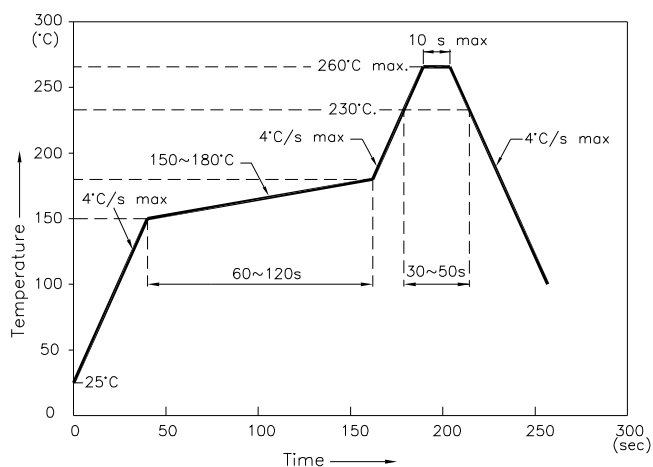
Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions
$V_{BR\ CE0}$	Collector-to-Emitter Breakdown Voltage	30	-	-	V	$I_C=100\mu\text{A}$ $E_e=0\text{mW}/\text{cm}^2$
$V_{BR\ EC0}$	Emitter-to-Collector Breakdown Voltage	5	-	-	V	$I_E=100\mu\text{A}$ $E_e=0\text{mW}/\text{cm}^2$
$V_{CE\ (SAT)}$	Collector-to-Emitter Saturation Voltage	-	-	0.8	V	$I_C=2\text{mA}$ $E_e=20\text{mW}/\text{cm}^2$
$I_{CEO}$	Collector Dark Current	-	-	100	nA	$V_{CE}=10\text{V}$ $E_e=0\text{mW}/\text{cm}^2$
$T_R$	Rise Time (10% to 90% )	-	3	-	us	$V_{CE}=5\text{V}$ $I_C=1\text{mA}$ $R_L=1000\Omega$
$T_F$	Fall Time (90% to 10% )	-	3	-	us	
$I_{(ON)}$	On State Collector Current	0.1	0.3	-	mA	$V_{CE}=5\text{V}$ , $E_e=1\text{mW}/\text{cm}^2$ , $\lambda=940\text{nm}$
$2\theta_{1/2}$	Viewing Angle	-	120	-	deg	-

## Absolute Maximum Ratings at $T_A=25^{\circ}\text{C}$

Parameter	Max.Ratings
Collector-to-Emitter Breakdown Voltage	30V
Emitter-to-Collector Breakdown Voltage	5V
Power Dissipation at (or below) $25^{\circ}\text{C}$ Free Air Temperature	100mW
Operating Temperature Range	$-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$
Storage Temperature Range	$-40^{\circ}\text{C} \sim +85^{\circ}\text{C}$

## KP-1608P1C

Reflow Soldering Profile For Lead-free SMT Process.



**NOTES:**

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

### Recommended Soldering Pattern (Units : mm)



### Tape Specifications (Units : mm)

